

⚠ Caution · Notice

■ ⚠ Caution (Storage and Operating Conditions)

This product is designed for application in an ordinary environment (normal room temperature, humidity and atmospheric pressure). Do not use under the following conditions because all of these factors can deteriorate the characteristics or cause product failure and burn-out.

1. Corrosive gas or deoxidizing gas (Chlorine gas, Hydrogen sulfide gas, Ammonia gas, Sulfuric acid gas, Nitric oxide gas, etc.)
2. Volatile or flammable gas
3. Dusty conditions

■ ⚠ Caution (Others)

Be sure to provide an appropriate fail-safe function on your product to prevent secondary damage that may be caused by the abnormal function or the failure of our product.

■ Notice (Storage and Operating Conditions)

To keep solderability of product from declining, the following storage conditions are recommended.

1. Storage Condition:
Temperature -10 to +40°C
Humidity less than 75%RH (not dewing condition)
2. Storage Term:
Use this product within 6 months after delivery by first-in and first-out stocking system.
3. Handling after Unpacking:
After unpacking, promptly reseal this product or store it in a sealed container with a drying agent.
4. Storage Place:
Do not store this product in corrosive gas (Sulfuric acid, Chlorine, etc.) or in direct sunlight.

■ Notice (Handling)

1. Do not give this product a strong press-force nor a mechanical shock. Because such mechanical forces may cause cracking or chipping of this ceramic product.
2. Rapid cooling or heating during soldering is not recommended.
Such treatment may destroy the element.
3. When this product is operated, temperature of some area may be over 100 to 150°C. Be sure that surrounding parts and inserting material can withstand the temperature. If the surrounding part and material is kept under such condition, they may be deteriorated or may produce harmful gases (Cl₂, H₂S, NH₃, SO_x, NO_x etc.). And, such harmful gas may deteriorate the element.
4. Do not assemble this product with air-sealing or resin casting. Such sealing may deteriorate the characteristic or destroy PTC element.
5. Location on Printed Circuit Board (PC Board)

4. Under vacuum, or under high or low pressure
5. Wet or humid conditions
6. Places with salt water, oils, chemical liquids or organic solvents
7. Strong vibrations
8. Other places where similar hazardous conditions exist

